

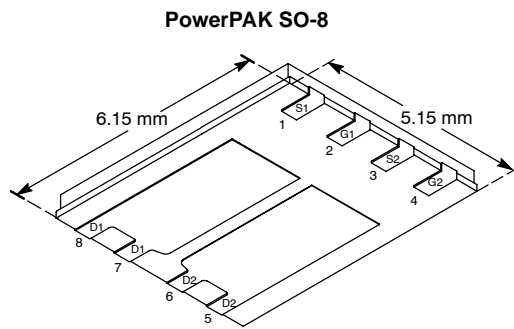


## Dual N-Channel 40-V (D-S) MOSFET

<b>PRODUCT SUMMARY</b>			
$V_{DS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)	$Q_g$ (Typ)
40	0.017 @ $V_{GS} = 10$ V	11.1	46.2

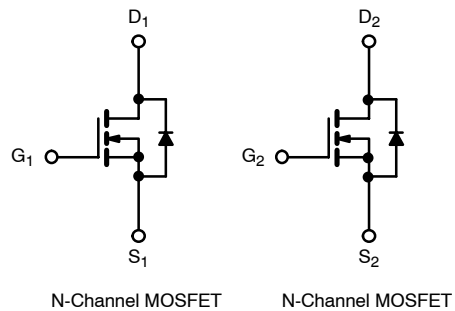
### FEATURES

- TrenchFET® Power MOSFET
- New Low Thermal Resistance PowerPAK® Package
- Dual MOSFET for Space Savings
- 100%  $R_g$  Tested
- High Threshold Voltage At High Temperature



Bottom View

Ordering Information: Si7962DP-T1—E3



N-Channel MOSFET

N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS (<math>T_A = 25^\circ\text{C}</math> UNLESS OTHERWISE NOTED)</b>				
Parameter	Symbol	10 secs	Steady State	Unit
Drain-Source Voltage	$V_{DS}$	40		V
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ ) <sup>a</sup>	$I_D$	$T_A = 25^\circ\text{C}$ 11.1	$T_A = 25^\circ\text{C}$ 7.1	A
		$T_A = 70^\circ\text{C}$ 8.9	$T_A = 70^\circ\text{C}$ 5.7	
Pulsed Drain Current	$I_{DM}$	40		
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	2.9	1.2	
Single Avalanche Current	$I_{AS}$	30		
Single Avalanche Energy	$E_{AS}$	45		mJ
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_A = 25^\circ\text{C}$ 3.5	$T_A = 25^\circ\text{C}$ 1.4	W
		$T_A = 70^\circ\text{C}$ 2.2	$T_A = 70^\circ\text{C}$ 0.9	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150		$^\circ\text{C}$

<b>THERMAL RESISTANCE RATINGS</b>					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	$R_{thJA}$	$t \leq 10$ sec 26	35	$^\circ\text{C/W}$	
		Steady State 60	85		
Maximum Junction-to-Case (Drain)	$R_{thJC}$	2.2	2.7		

**Notes**

a. Surface Mounted on 1" x 1" FR4 Board.

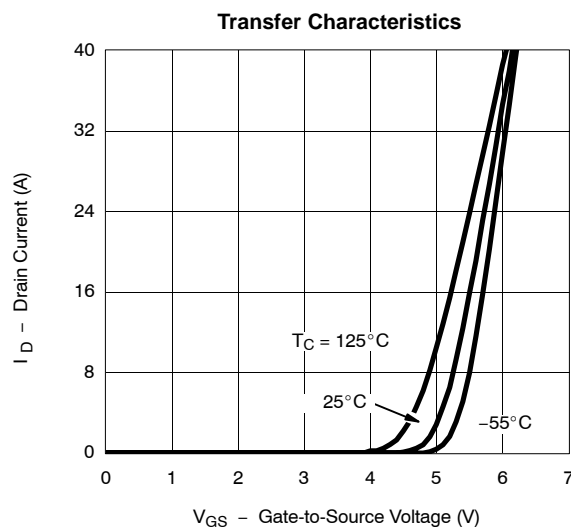
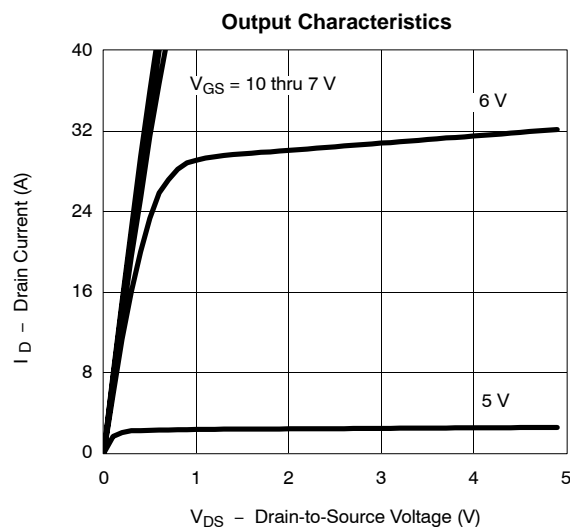
**SPECIFICATIONS (T<sub>J</sub> = 25 °C UNLESS OTHERWISE NOTED)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.4		4.5	V
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V			1	μA
		V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			5	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5 V, V <sub>GS</sub> = 10 V	30			A
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11.1 A		0.0135	0.017	Ω
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 11.1 A		31		S
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = 2.9 A, V <sub>GS</sub> = 0 V		0.8	1.2	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11.1 A		46.2	70	nC
Gate-Source Charge	Q <sub>gs</sub>			16		
Gate-Drain Charge	Q <sub>gd</sub>			9.6		
Gate Resostamce	R <sub>g</sub>	f = 1 MHz	1.1	2.3	3.5	Ω
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 20 V, R <sub>L</sub> = 20 Ω I <sub>D</sub> ≅ 1 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 6 Ω		22	35	ns
Rise Time	t <sub>r</sub>			15	25	
Turn-Off Delay Time	t <sub>d(off)</sub>			55	70	
Fall Time	t <sub>f</sub>			15	25	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 2.9 A, di/dt = 100 A/μs		35	60	

## Notes

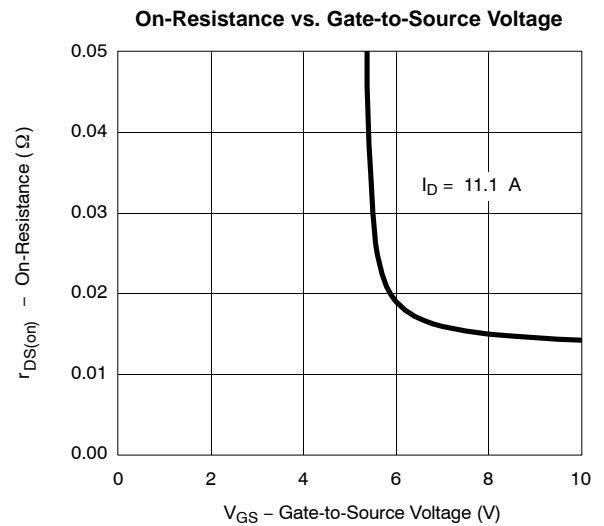
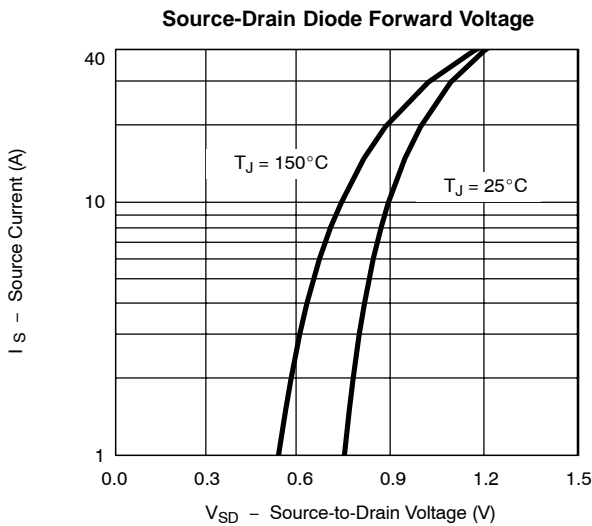
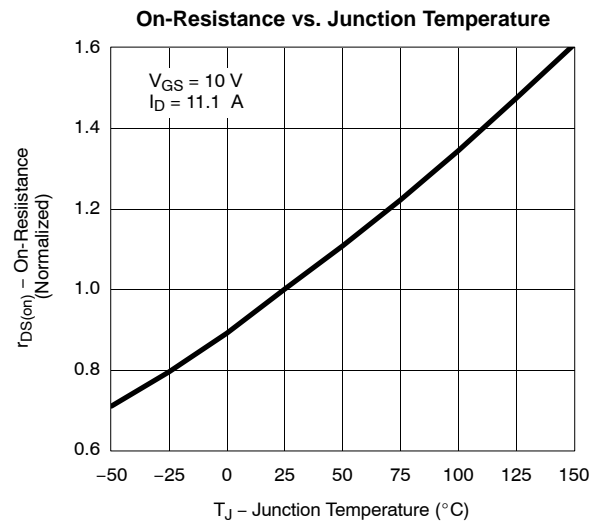
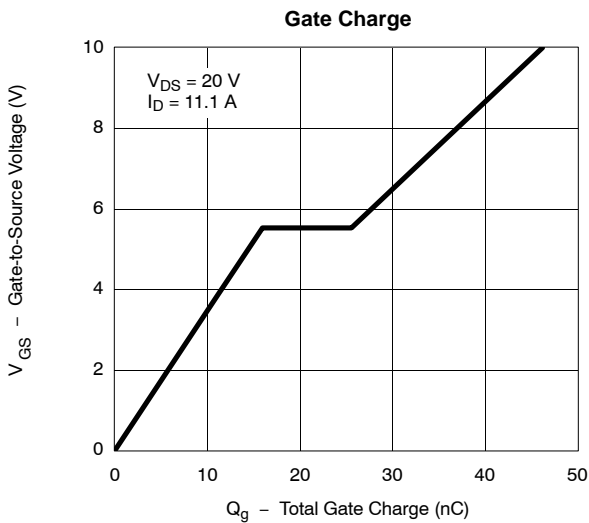
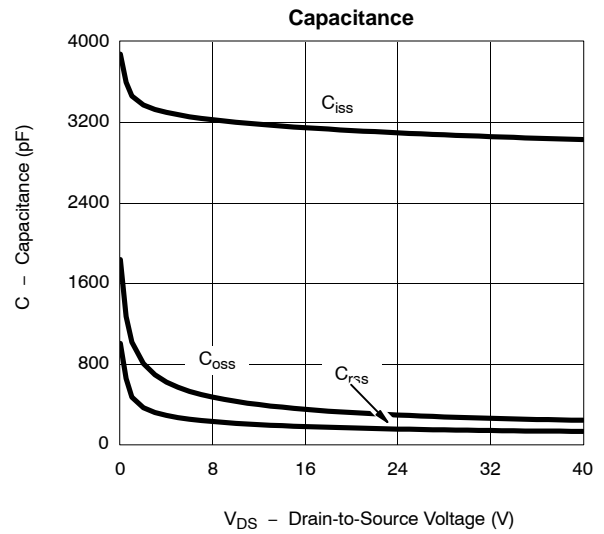
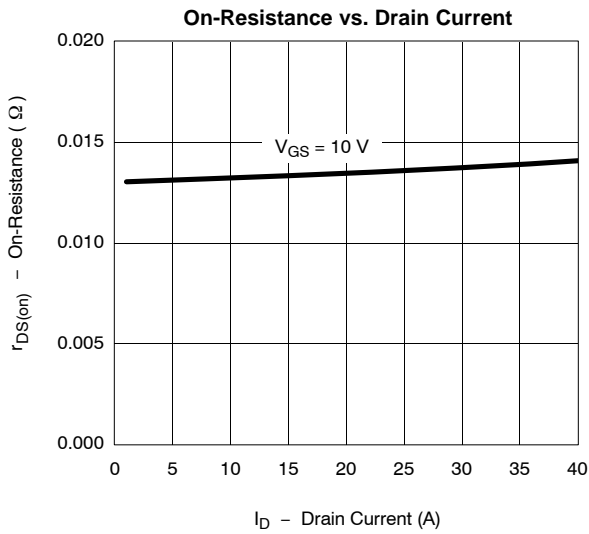
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.  
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

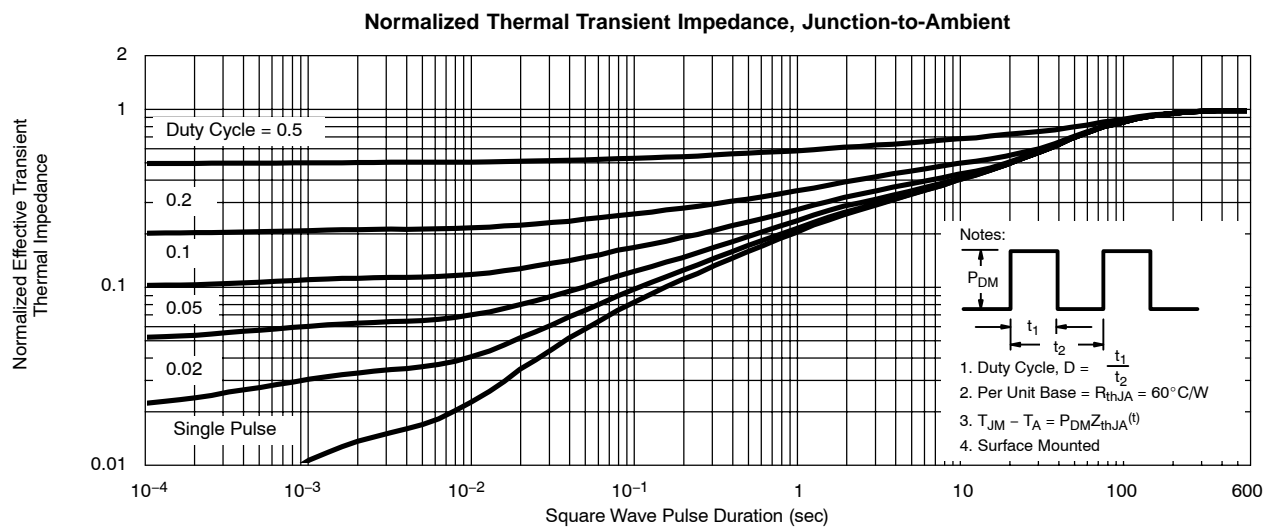
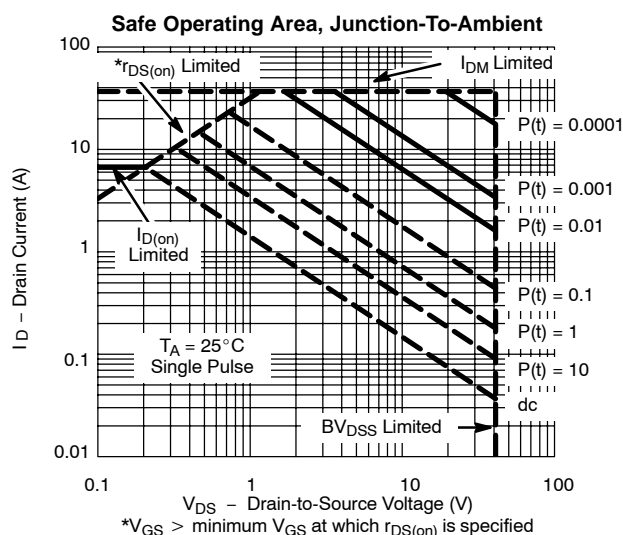
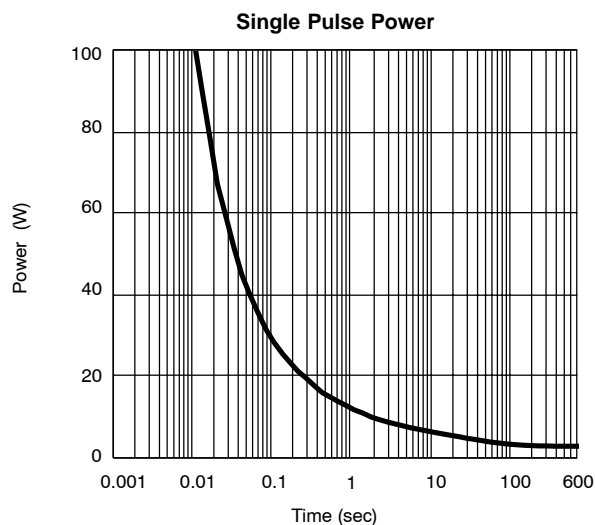
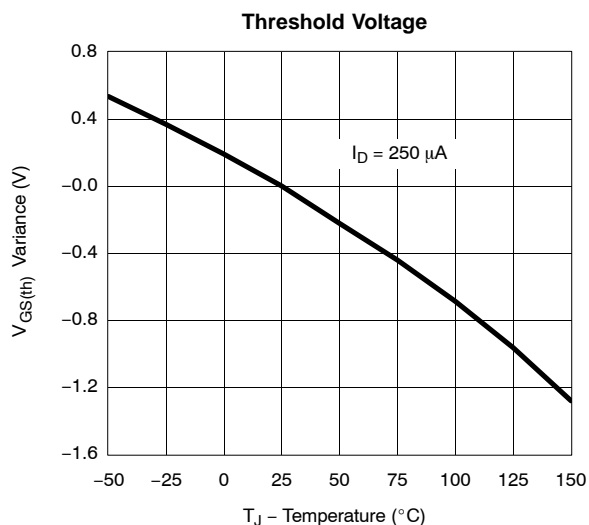
**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**



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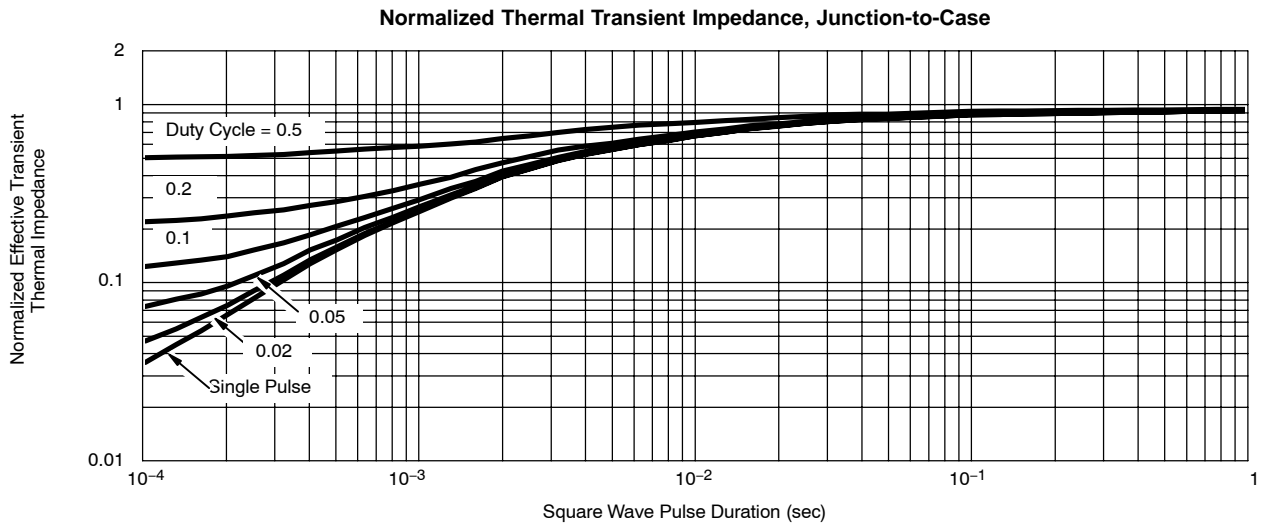


**TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**





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